

ABSTRACT OF THE DISCLOSURE

A semiconductor device is made by mounting semiconductor elements on both sides of a wiring board having three-dimensional wiring including inner-via holes. A high operating speed and smaller size are made possible by employing a laminated structure of semiconductor elements without using the chip-on-chip configuration. Semiconductor elements are mounted on both sides of a wiring board having three-dimensional wiring including inner via holes so that the semiconductor elements oppose each other via the wiring board. The electrodes of the semiconductor elements are connected with each other by the three-dimensional wiring of the wiring board.